

New Phase Change Material Expands Company's Thermal Interface Materials Product Line



Laird Technologies, Inc. announced the release of its new Tpcm[®] 580SP Series phase change material. The Tpcm[®] 580SP Series is the latest phase change material (PCM) offered in Laird Technologies' thermal interface material (TIM) product line. It is an exceptionally high-performance, screen printable or stencilable TIM with a thermal conductivity of 4.0 W/mK that provides an alternative to thermal grease.

The PCM pad contains a solvent that assists in processing, which allows for wetting of the surface. After drying, the solvent is moistureless to the touch, and therefore eliminates the mess associated with thermal grease. Once the solvent is removed, Tpcm[®] 580SP begins to soften and flow at temperatures around 45°C, minimizing thermal contact resistance by filling in the microscopic irregularities of the components it touches. Because Tpcm[®] 580SP softens but does not fully change states, it minimizes migration (pump out) under thermal cycling from room temperature to chip device operating temperatures.

The Tpcm[®] 580SP series is available in a 0.5 kg or 1.0 kg can for easy manual screen printing and large volume automatic operations. It is ideal for a variety of applications including high frequency microprocessors, notebook PCs, desktop PCs, computer servers, DC/DC converters, memory modules, cache chips, IGBTs, and automotive and optical electronics.

Source URL (retrieved on 01/25/2015 - 5:54pm):

<http://www.wirelessdesignmag.com/product-releases/2011/04/new-phase-change-material-expands-company%C3%A2%E2%82%AC%E2%84%A2s-thermal-interface-materials-product-line>

